



**JUFENG** JUFENG was found in 2006 with three factories for manufacturing solder wire, solder bar, solder paste, flux, solder powder, solder preform, solder ball, solder foil, water-based cleaning agent, etc.

## Product Range

- **Solder wire:** 0.1mm~6.0mm diameter
- **Solder Powder:** Type 2.3 ~ Type 9
- **Solder Paste:** Type 3 ~ Type 6 (5-15um), ROL0, RMA, ROL1
- **Solder Sphere:** 0.05mm~0.889mm customer-made available, Tolerance 5um

## New

- **Low Temperature Solder Wire:** Flux cored Tin Bismuth wire, flux cored Indium wire
- **Solder Powder:** Type 8, Type 9
- **Solder Paste:** Type 7 Mini LED solder paste
- **Solder Sphere:** Low temperature sphere



**IATF16949 认证 / ISO9001**



**Water-based Cleaner**

Non-toxic, safe, non-burning, non-damaging to the environment, long service life. The water based cleaner can be degraded and has minimal harm to the human body. Completely eliminate fire safety hazards and continuously improve environmental protection material level requirements to meet current environmental protection regulations such as ROHS, HF, REACH, SONY00259

**Low Temp Flux-cored Solder Wire**

1. 138°C melting point
2. Rosin Core solder wire diameter  $\geq 0.8\text{mm}$ , Solid core solder wire diameter  $\geq 0.25\text{mm}$
3. Good toughness, it is not easy to break and can be used on automatic welding machine
4. According to customer's welding request, it can be made into solid core or rosin core, Water-solution or No clean, halogenated or halogen-free
5. Suitable for heat-sensitive parts, widely used in electronic welding stepwise welding (secondary welding), TV adjusters, fire alarms, temperature control parts, lighting protection equipment, air conditioning safety protectors, etc.

**Solder Preforms**

The pre-coated flux solder sheet is pre-coated with excellent flux on the original solder sheet to improve the oxidation resistance of the solder sheet. It can be soldered directly with equipment, or through reflow soldering or induction soldering. Compared with solder wire or solder paste, it simplifies the manufacturing process, the solder soldering machine is quantitative, and the residue is reduced.

**Halogen Free BGA Flux Paste**

A kind of no-clean, environmentally friendly solder paste, which can be widely used in the maintenance of mobile phones and computer boards, as well as the production of BGA balls and other electronic components. It adopts a highly reliable low-ion activator system. There are very few residues after soldering and very high insulation resistance, even without washing, it can have extremely high reliability

**Ultra-Thin Solder Wire 0.1mm**

Alloy content	Sn96.5-Ag3.0-Cu0.5	Test method
Flux content	1.0-3.0%	IPC-TM-650 2.3.34.1
diameter	0.1-6.0mm	-
Halide content	ROL0 (J-STD-004)	IPC-TM-650 2.3.35
Copper mirror corrosion test	PASS	IPC-TM-650 2.6.15
Copper mirror test	PASS	IPC-TM-650 2.6.32
SIR	PASS	IPC-TM-650 2.6.3.3
EMC	PASS	IPC-TM-650 2.6.14.1

**Solder Sphere**

**Product advantages:**  
Uniform roundness, small diameter tolerance, good oxidation resistance, excellent weldability, and strong reliability

**Applications:**  
Suitable for BGA packaging, CSP process packaging, semiconductor packaging, SMT repair, camera modules, etc.

**Ultra-Fine Solder Powder**

High purity, low oxygen content  
Good sphericity and concentrated particle size distribution  
It can mass produce #6, #7, #8, #9 powder  
Applicable to 5G, semiconductor



